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(12) **United States Design Patent**
Okada et al.

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(54) **PATTERN WAFER**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**

USPC D13/182; D6/309

CPC C30B 25/02; C30B 25/04; C30B 25/12; C30B 25/18; C30B 25/186; C30B 25/20;

H01L 21/2018; H01L 21/2003; H01L 21/02367; H01L 21/0237; H01L 21/02428; H01L 21/0243; H01L 21/02433; H01L 21/02436; H01L 21/31116; H01L 21/32139; H01L 21/31144; H01L 21/0337; H01L 21/31138; H01L 21/02439; H01L 21/3213; H01L 21/32131; H01L 21/32133; H01L 21/32135; H01L 21/823807; H01L 21/84; H01L 21/31055; H01L 21/31053; H01L 21/76819; H01L 21/31111; H01L 33/16; H01L 29/02;

H01L 29/04; H01L 29/045; H01L 29/06; H01L 29/0603; H01L 29/66765; H01L 29/66757; H01L 27/1203; H01L 27/1218; H01L 27/1222; H01S 5/3202

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a pattern wafer, as shown and described.

DESCRIPTION

FIG. 1 is a front elevational view of a pattern wafer, showing our new design;

FIG. 2 is a rear elevational view thereof;

FIG. 3 is a left side elevational view thereof;

FIG. 4 is a right side elevational view thereof;

FIG. 5 is a top plan view thereof;

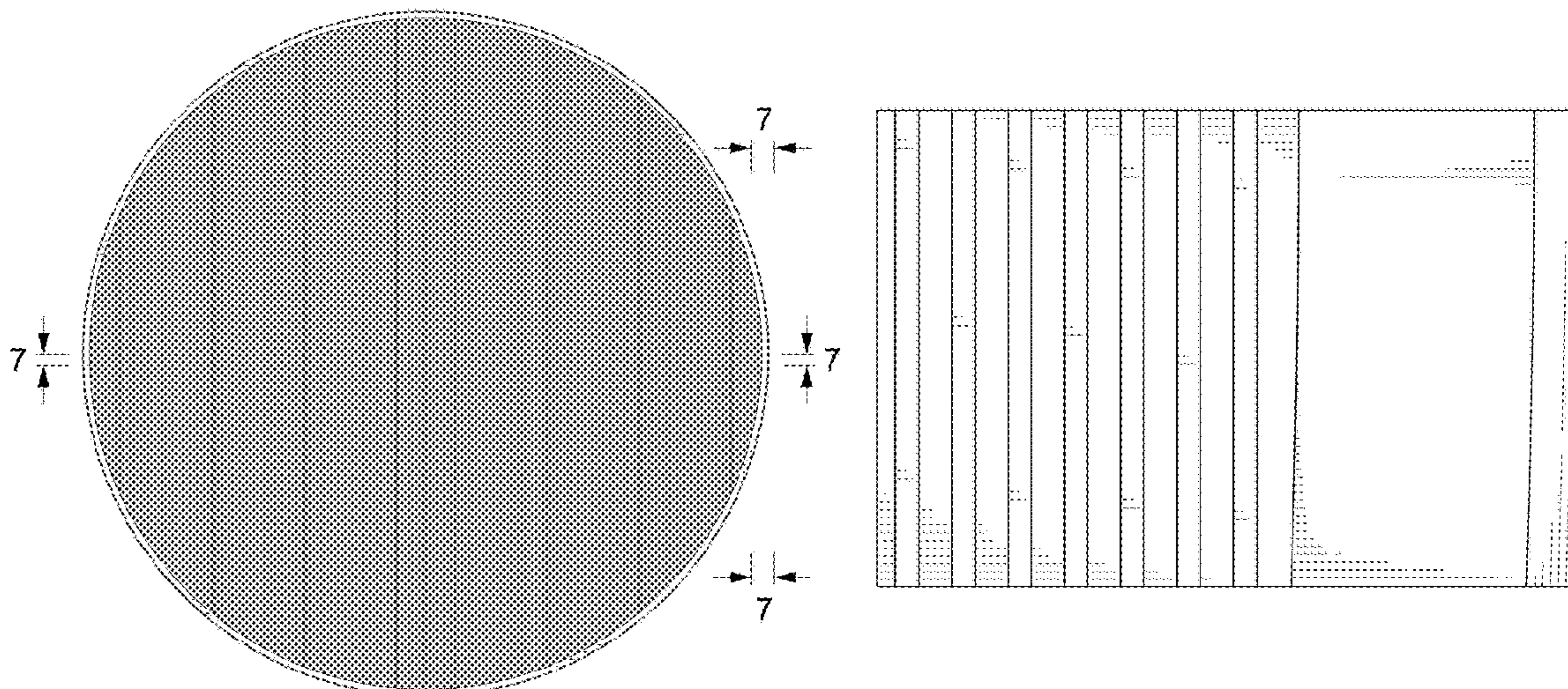
FIG. 6 is a bottom plan view thereof;

FIG. 7 is an enlarged front portion view taken along line 7-7 in FIG. 1;

FIG. 8 is an enlarged bottom portion view taken along line 8-8 in FIG. 6; and,

FIG. 9 is a top perspective view of FIG. 7.

1 Claim, 5 Drawing Sheets



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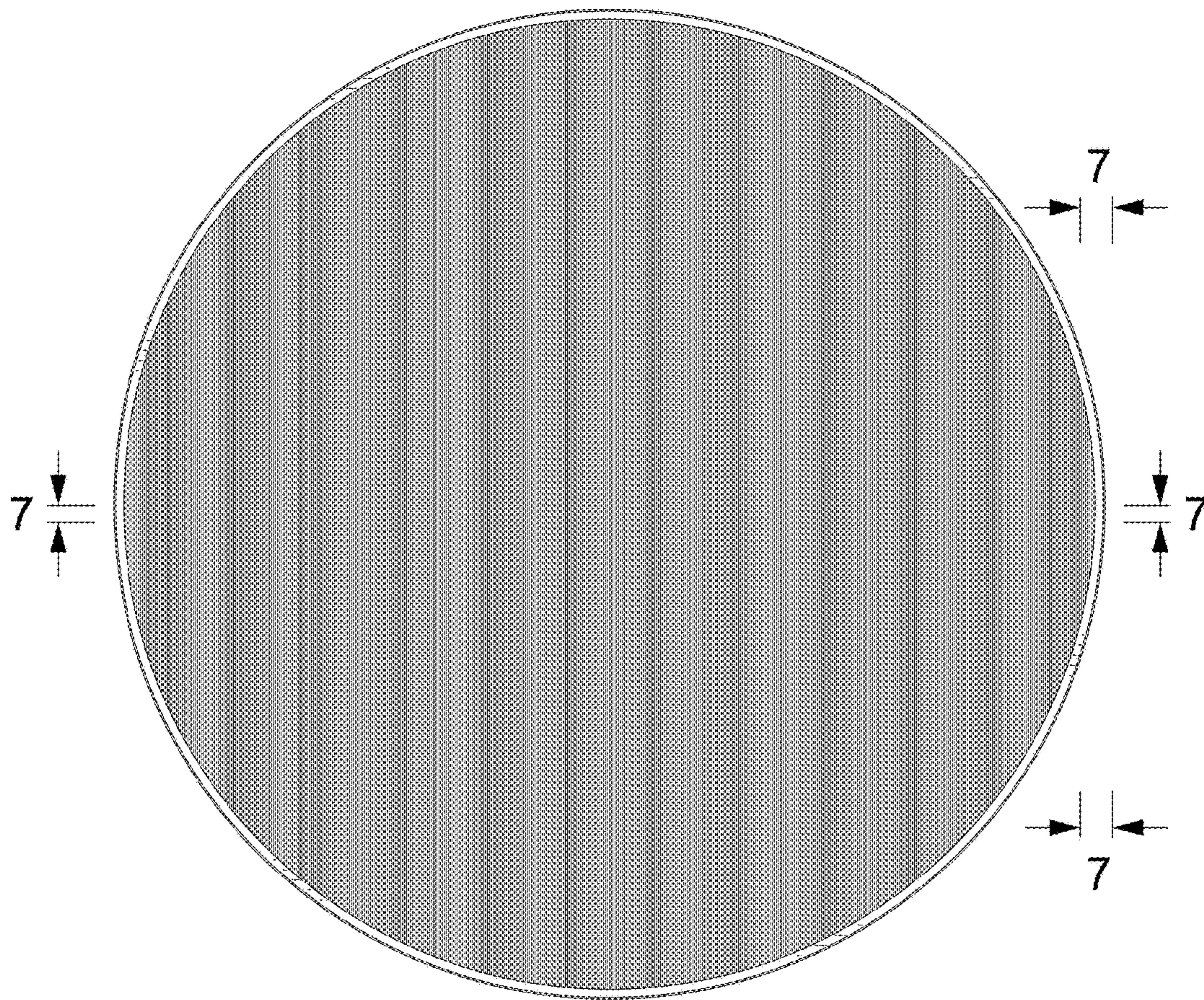


FIG. 1

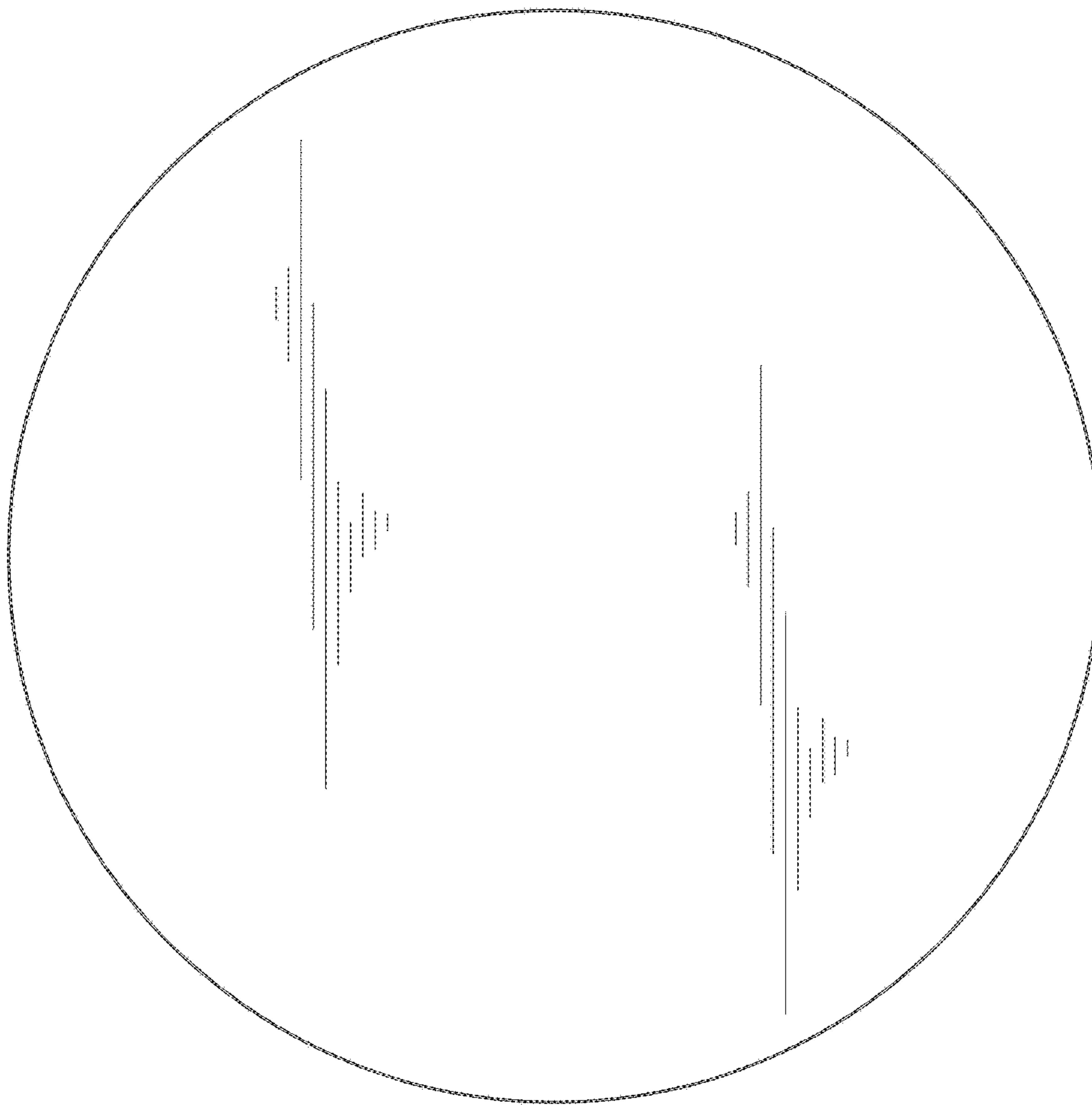


FIG. 2



FIG. 3



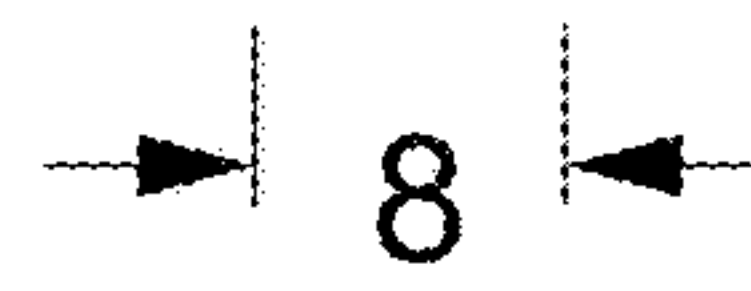
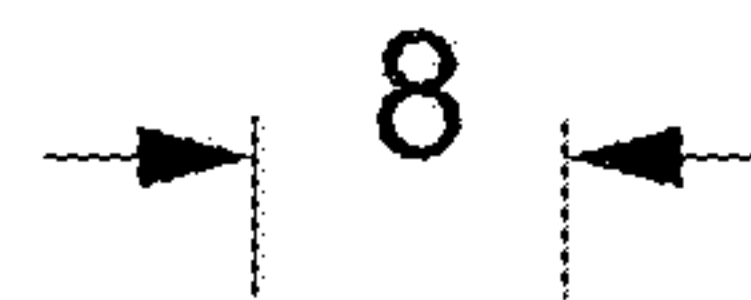
FIG. 4



FIG. 5



FIG. 6



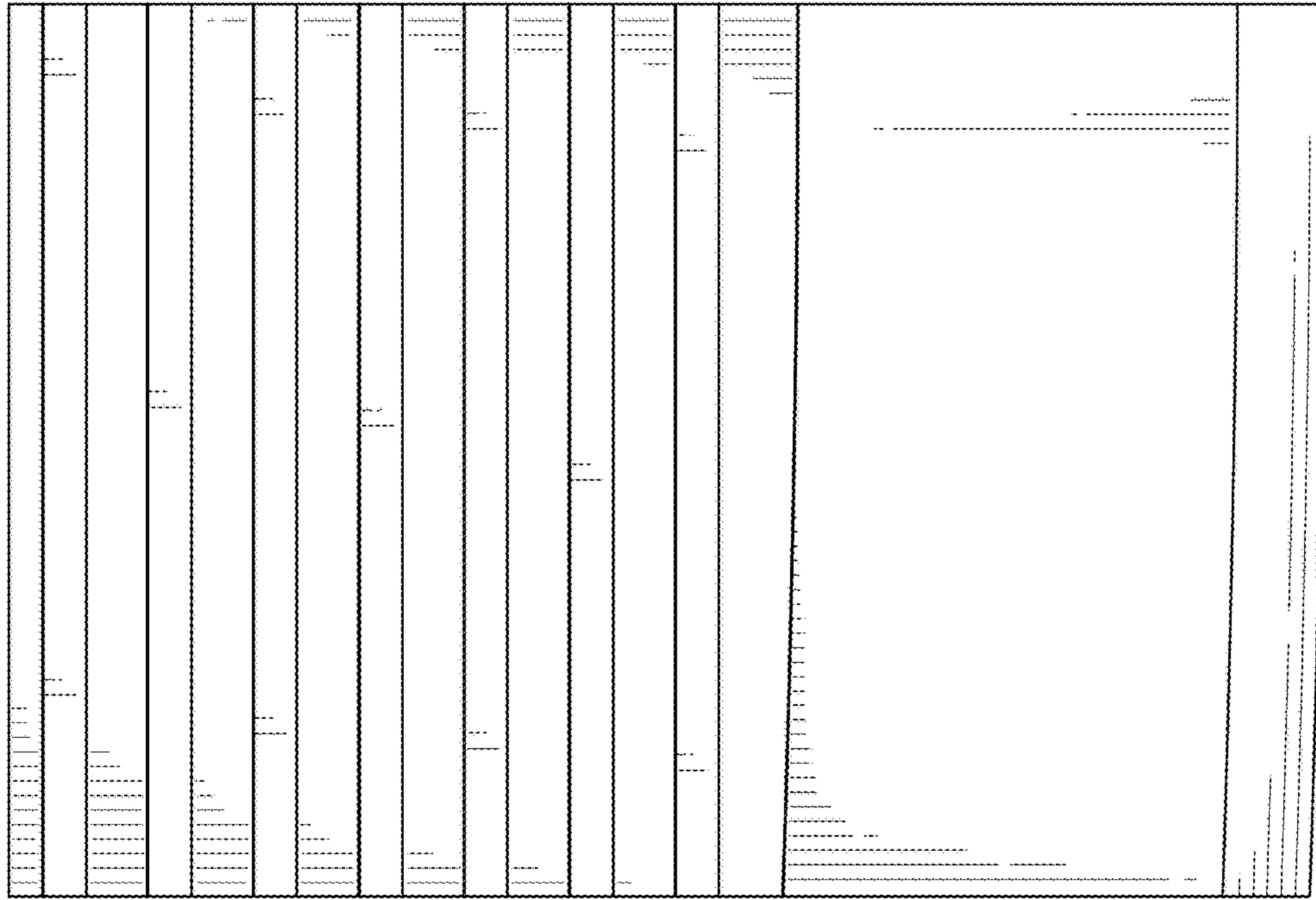


FIG. 7

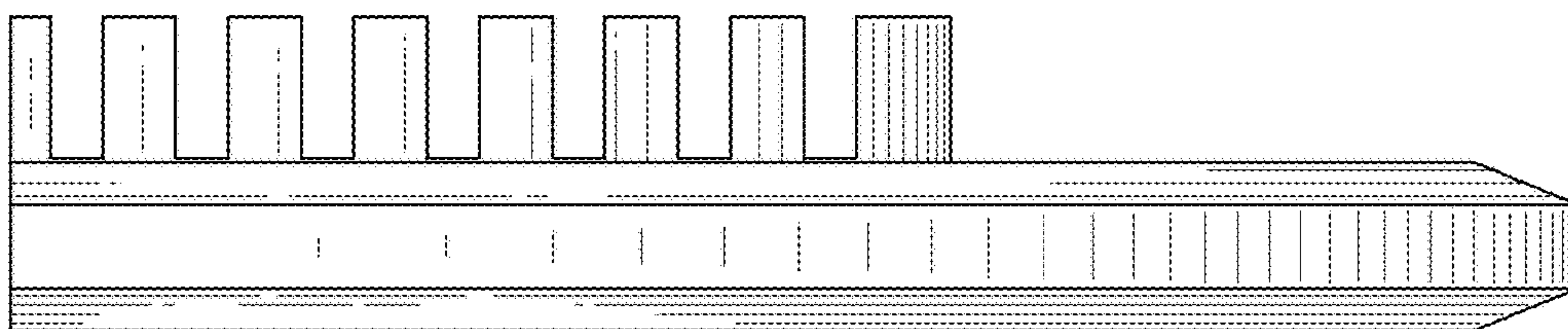


FIG. 8

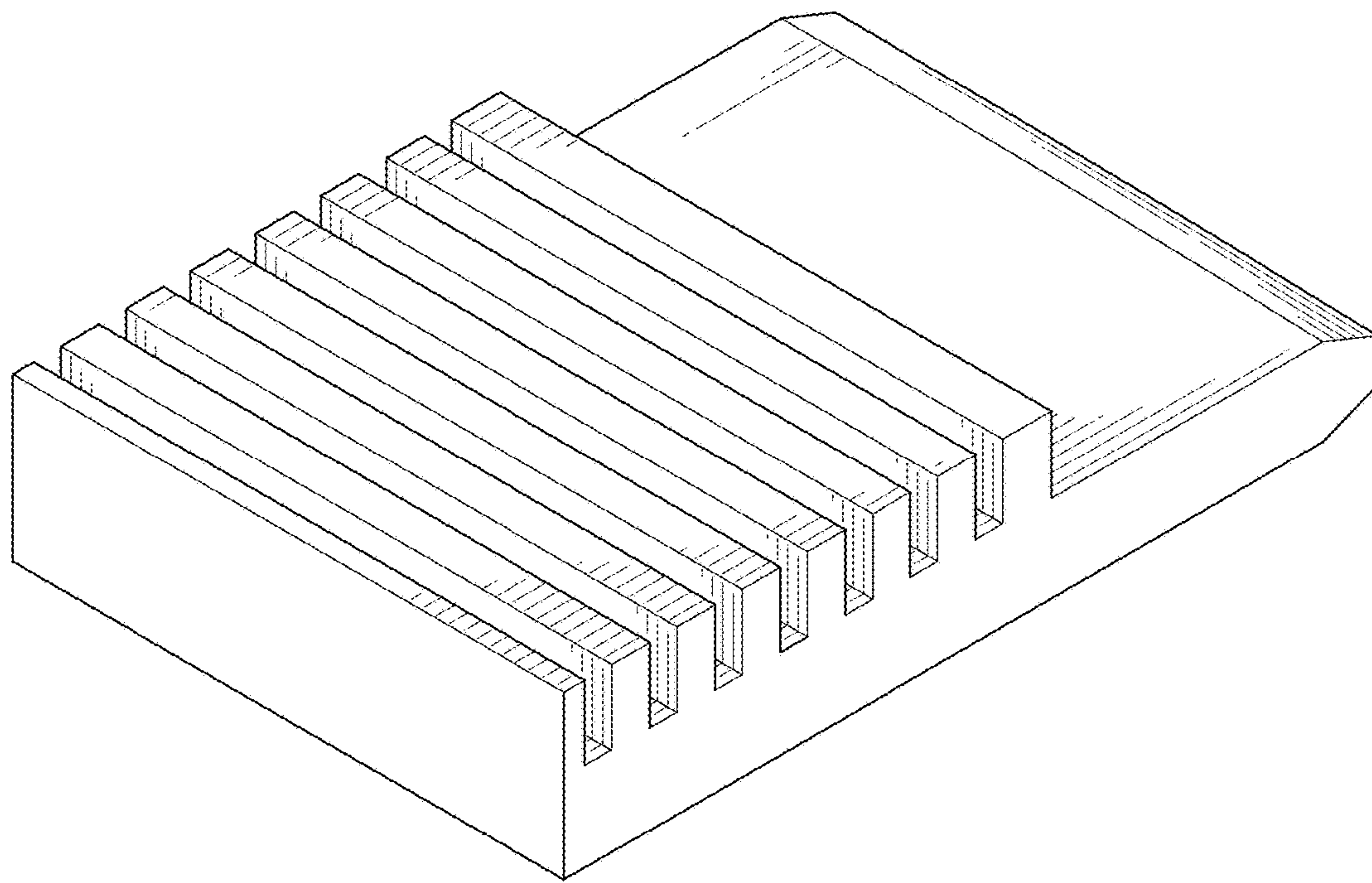


FIG. 9